## CLAIMS

[Claim 1] A substrate processing apparatus comprising:

a plurality of polishing modules each configured to polish a substrate, the plurality of polishing modules being located in a polishing level;

a first post-processing lane and a second post-processing lane each configured to perform post-processing including cleaning and drying of the polished substrate, the first post-processing lane and the second post-processing lane being located in a post-processing level; and

an elevating transporter configured to remove the polished substrate from one of the plurality of polishing modules and transport the polished substrate directly to the first post-processing lane or the second post-processing lane,

wherein the post-processing level is an upper level located above the polishing level or a lower level located below the polishing level,

the elevating transporter is located at the same distance from the plurality of polishing modules,

the elevating transporter includes a holding hand configured to hold the substrate and an elevating mechanism configured to elevate and lower the holding hand between the polishing level and the post-processing level, and

the elevating transporter is located at the same distance from the first post-processing lane and the second post-processing lane.

[Claim 2] The substrate processing apparatus according to claim 1, wherein the plurality of polishing modules comprise four polishing modules, and the elevating transporter is located at the same distance from the four polishing modules and is surrounded by the four polishing modules.

[Claim 3] The substrate processing apparatus according to claim 1, wherein the elevating transporter further includes an inverting device configured to invert the holding

hand.

[Claim 4] The substrate processing apparatus according to claim 1, further comprising:

a substrate transfer robot configured to remove the substrate to be polished from a cassette storage, remove the post-processed substrate from the first post-processing lane or the second post-processing lane, and return the post-processed substrate to the cassette storage; and

a vertical movement mechanism configured to elevate and lower the substrate transfer robot between the polishing level and the post-processing level.

[Claim 5] The substrate processing apparatus according to claim 1, wherein the first post-processing lane and the second post-processing lane are arranged in parallel at the same height in the post-processing level.

[Claim 6] The substrate processing apparatus according to claim 1, wherein each of the first post-processing lane and the second post-processing lane includes a cleaning module and a drying module arranged in a row.

[Claim 7] The substrate processing apparatus according to claim 1, wherein the first post-processing lane and the second post-processing lane are adjacent to the substrate transfer robot.

[Claim 8] The substrate processing apparatus according to claim 1, wherein each of the plurality of polishing modules has a polishing head configured to polish the substrate and a substrate loader configured to receive the substrate from the elevating transporter and transfer the substrate to the polishing head, and

the elevating transporter is located at the same distance from the substrate loaders

of the plurality of polishing modules.

[Claim 9] The substrate processing apparatus according to claim 1, wherein the plurality of polishing modules comprise six polishing modules,

the elevating transporter is a first elevating transporter,

the first elevating transporter is located at the same distance from at least three of the plurality of polishing modules,

the substrate processing apparatus further comprises:

a second elevating transporter located at the same distance from remaining polishing modules of the plurality of polishing modules,

a third post-processing lane arranged in the post-processing level, and

a return transporter configured to transport the substrate that was post-processed by the third post-processing lane to the substrate transfer robot, and

the second elevating transporter is configured to remove the polished substrate from one of the remaining polishing modules and transport the polished substrate directly to the third post-processing lane.